

Claim Rejections 35 U.S.C. § 102 (b)

The Examiner has rejected claims 54, 55, 58-60, and 63-65 under 35 U.S.C. §102 (b) as being anticipated by Burke et al. (US 5,645,469).

Applicants respectfully disagree with the Examiner. Applicants have canceled claims 55, 58, 60, 63, and 65 without prejudice. Applicants have amended claims 54, 59, and 64. Support for amending claims 54, 59, and 64 is provided at lines 17-18 and 21-23 on page 13 of the specification. Also, see Figures 3 and 7. Applicants have added new claims 68-79.

Claim 54, as amended, of Applicants' claimed invention claims a polish pad including: a first set of grooves located in a first area, the first set of grooves having a first depth; and a second set of grooves located in a second area, the second set of grooves having a second depth where the first depth is smaller than the second depth to reduce polish rate in the first area.

Claim 59, as amended, of Applicants' claimed invention claims a polish pad including: a first set of grooves located in a first area, the first set of grooves having a first width; and a second set of grooves located in a second area, the second set of grooves having a second width where the first width is smaller than the second width to reduce polish rate in the first area.

Claim 64, as amended, of Applicants' claimed invention claims a polish pad including: a first set of grooves located in a first area, the first set of grooves having a first density; and a second set of grooves located in a second area, the second set of grooves having a second density where the first density is smaller than the second density to reduce polish rate in the first area.

In contrast, the cited reference of Burke et al. teaches a first polish pad (10) with a polishing surface (12) having radially extending tapered channels (20) arranged in a "sunburst" pattern and circumferential grooves (26) outside the channels. See Figures 1-2. Also, see Col. 4, lines 42-44 and 56-58.

The cited reference of Burke et al. also teaches a second polish pad (30) with a polishing surface (32) having radially extending tapered channels (40) arranged in a "starfish" pattern and circumferential grooves (46) outside the channels. See Figures 3-4. Also, see Col. 5, lines 24-26 and 39-42.

Thus, the Burke et al. reference cited by the Examiner does not teach that depth, width, and density of grooves may be smaller in an area of a pad to reduce polish rate in that area. Since the Burke et al. reference cited by the Examiner does not teach each and every element of Applicants' claimed invention as claimed in claims 54, 59, and 64, as amended, the cited reference of Burke et al. does not anticipate claims 54, 59, and 64, as amended, of Applicants' claimed invention.

In view of the foregoing, Applicants respectfully requests the Examiner to withdraw the rejections to claims 54, 59, and 64, as amended, under 35 U.S.C. §102 (b).

Claim Rejections 35 U.S.C. § 103 (a)

The Examiner has rejected claims 56, 57, 61, 62, 66, and 67 under 35 U.S.C. §103 (a) as being unpatentable over Burke et al. (US 5,645,469).

Applicants have canceled claims 56, 57, 61, 62, 66, and 67 without prejudice.


Conclusion

Applicants believe that all pending claims, including amended claims and new claims, are now in condition for allowance so such action is earnestly solicited at the earliest possible date.

If there are any additional charges, please charge Deposit Account No. 02-2666. If a telephone interview would in any way expedite the prosecution of this application, the Examiner is invited to contact the undersigned at (408) 720-8300.

Respectfully submitted,
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